## Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

## **Listing of Claims:**

Please amend the claims as follows:

1. (Currently Amended) A resin composition for encapsulating a semiconductor chip comprising:

an epoxy resin (A) represented by general formula (1):

wherein R represents hydrogen or alkyl having up to four carbon atoms; and n is a positive number from 1 to 10 as an average;

a phenol resin (B) represented by general formula (2):

H 
$$CH_2 - R_1 - CH_2$$
 $R_2$ 
 $R_2$ 
 $R_2$ 

wherein R<sub>1</sub> represents phenylene or biphenylene; R<sub>2</sub> represents <u>hydrogen or</u> alkyl having up to four carbon atoms; and n is a positive number from 1 to 10 as an average;

an inorganic filler (C);

a curing accelerator (D);

a silane coupling agent (E); and

Compound (F) containing two and more hydroxyl groups on eombined with each of adjacent carbon atoms eomprising in an aromatic ring.

- (Original) The resin composition for encapsulating a semiconductor chip according to Claim 1, wherein the resin composition comprises said Compound (F) in more than or equal to 0.01 wt%.
- (Original) The resin composition for encapsulating a semiconductor chip according to Claim 1, wherein the resin composition comprises said silane coupling agent (E) in 0.01 wt% to 1 wt% both inclusive.
- (Currently Amended) The resin composition for encapsulating a semiconductor chip
  according to Claim 1, wherein said compound (F) contains two hydroxyl groups on eembined
  with each of adjacent carbon atoms comprising in said aromatic ring.
- (Previously Presented) he resin composition for encapsulating a semiconductor chip according to Claim 1, wherein the aromatic ring is a naphthalene ring in Compound (F).
- (Currently Amended) The resin composition for encapsulating a semiconductor chip
  according to Claim 5, wherein said Compound (F) contains two hydroxyl groups on embined
  with each of adjacent carbon atoms eomprising in said naphthalene ring.
- (Original) The resin composition for encapsulating a semiconductor chip according to Claims 1, wherein the resin composition comprises said inorganic filler (C) in 84 wt% to 90 wt% both inclusive.
- (Previously Presented) A semiconductor device wherein a semiconductor chip is encapsulated by the resin composition according to Claim 1.

(Previously Presented) The resin composition for encapsulating a semiconductor chip according to Claim 1,

wherein said inorganic filler (C) is present in an amount of 84 wt% to 90 wt% both inclusive.

said silane coupling agent (E) is present in an amount of  $\,0.01$  wt% to 1 wt% both inclusive, and

said Compound (F) is present in an amount of  $\,0.01\,$  wt% to  $0.5\,$  wt% both inclusive.